



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS50010-1TAD		<b>Issued</b>		24. January 2018		
<b>MA#</b>		MA001605480						
<b>Package</b>		PG-TO263-7-10		<b>Weight*</b>		1558.38 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	14.178	0.91	0.91	9098	9098
leadframe	inorganic material	phosphorus	7723-14-0	0.247	0.02		159	
	non noble metal	iron	7439-89-6	0.823	0.05		528	
	non noble metal	copper	7440-50-8	822.375	52.77	52.84	527711	528398
	non noble metal	aluminium	7429-90-5	15.627	1.00	1.00	10028	10028
wire	non noble metal	aluminium	7429-90-5	15.627	1.00	1.00	10028	10028
encapsulation	organic material	carbon black	1333-86-4	8.270	0.53		5306	
	plastics	epoxy resin	-	90.965	5.84		58372	
	inorganic material	silicondioxide	60676-86-0	452.069	29.01	35.38	290089	353767
leadfinish	non noble metal	tin	7440-31-5	12.163	0.78	0.78	7805	7805
plating	inorganic material	phosphorus	7723-14-0	0.007	0.00		5	
	non noble metal	nickel	7440-02-0	2.941	0.19	0.19	1887	1892
glue	plastics	Polyimide	26023-21-2	0.198	0.01	0.01	127	127
solder	non noble metal	tin	7440-31-5	0.155	0.01		100	
	noble metal	silver	7440-22-4	0.194	0.01		124	
	non noble metal	lead	7439-92-1	7.409	0.48	0.50	4754	4978
heatspreader	inorganic material	phosphorus	7723-14-0	0.039	0.00		25	
	non noble metal	iron	7439-89-6	0.131	0.01		84	
	non noble metal	copper	7440-50-8	130.589	8.38	8.39	83798	83907
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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